# A UHF Proximity Micro-Transceiver for Mars Exploration

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Abstract—A UHF half-duplex micro-transceiver for future Mars exploration missions is described. The transceiver target specifications include a volume of less than 1 cm<sup>3</sup>, mass of less than 10 grams, and power consumption of <40 mW on receive and 50mW, 300mW, or 3W on transmit. It is compatible with a subset of Prox-1 protocols and supports transmission rates from 1 to 4096 ksps, depending on RF link parameters, in BPSK or OPSK format. Command and control instructions can be received at 1 or 8 ksps. In addition to its low mass/power features, temperature compensation to -100 C and radiation tolerance to 100 krad allow operation outside of large, thermally controlled, shielded enclosures, further reducing the mass and complexity of exploration vehicles. Although designed around Mars missions and environmental constraints, the transceiver is expected to be useful as well in other proximity links where a small/low-power radio compatible with Prox-1 protocols is desired.

# 1. INTRODUCTION

During the early decades of the twenty-first century, a series of robotic missions will be launched to support the exploration of Mars. Miniaturized, lightweight, and low-power systems are among the needed telecommunications technologies. Existing radio transceivers typically measure as large as 5000 cm<sup>3</sup>, weigh up to 5 kg, and consume more than 50 W on transmit and 10 W on receive. A transceiver measuring in the 1 cm<sup>3</sup> range and operating at fractions of a Watt will enable the design of new types of Mars exploration craft ranging from low-cost, low-mass, networked ground sensors/rovers to airplanes or balloons. The micro-transceiver will communicate collected scientific results to earth by relaying data through Mars orbiters already under development as well as support surface-to-surface links for geographically extended local exploration.

The top-level design and specifications are described in this paper, with emphasis on the analog/RF integrated circuit portion of the micro-transceiver. The development effort targets operation in the Mars temperature and radiation environment using a rad-hard Silicon-on-Sapphire (SOS) IC process [1-2], and leverages recent advancements in on-chip

power amplifier design techniques, resonant TR switch circuits, and the specific requirements of the Mars telecommunications environment. A companion paper [3] presents data on designing for the Mars environment temperature range of  $-100~\rm C$  to  $+25~\rm C$ .

# 2. System Architecture

A top-level block diagram illustrating the micro-transceiver in relation to a host vehicle is shown in Figure 1. The transceiver interfaces to a microprocessor on-board a scout craft and transmits collected data to an orbiter using the Microtransceiver Electronics through a suitable external antenna (nominally a low-mass wire monopole or dipole).

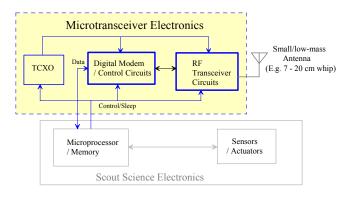


Figure 1. Top-level diagram of micro-transceiver and external interfaces.

Frequencies of operation and data formatting are a subset of those specified in the Proximity-1 Space Link Protocol recommendations [4]. The nominal uplink (micro-transceiver to Orbiter) frequency is 400 MHz, and the nominal downlink frequency is 440 MHz. Transmit power levels are selectable from 10 mW to 1 W to suit particular mission requirements. Data transmission is via suppressed or residual carrier BPSK modulation or via QPSK modulation at rates up to 256 ksps. Higher rates are supportable for local links [5]. The micro-transceiver also receives command and control data from the orbiter/relay. Command reception is limited to rates up to 8 ksps to reduce size and power consumption of digital circuits. Total power consumption on transmit can be as low as 50 mW

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and total power on receive can be reduced to less than 0.5 mW using a sleep mode conservation approach with a 1 % duty cycle.

A more detailed block diagram of the Micro-transceiver with internal interfaces shown is provided in Figure 2 and a mockup of what a final PCB could look like is shown in Figure 3. The transceiver consists of two primary integrated circuits (an RFIC and a digital IC) and an optional third IC for the 1 W output power option. Also included are a commercial temperature compensated crystal oscillator (TCXO) and IF filter, together with a small collection of surface mount passives providing required supply bypassing and optional antenna impedance-matching functions.

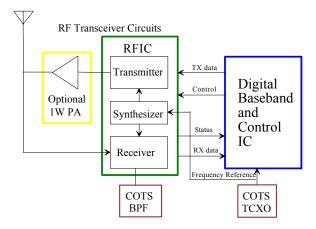


Figure 2. Simplified block diagram of micro-transceiver and internal interfaces.

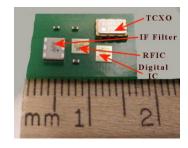


Figure 3. Physical mockup of full transceiver. 10/100mW version.

#### 3. DESIGN TRADEOFFS

The micro-transceiver is designed for exploration vehicles which require very low-volume, low-mass, and low-power electronics. The goal is to provide a medium performance UHF relay solution that is interoperable with the existing communications infrastructure. However, it is important to note that the low-power/low-mass/low-volume feature is the overriding goal. To meet this goal, many modes of operation that may be present on more traditional transceivers are excluded in this design. For example, power output is low 10/100 mW (or 1 W maximum using optional PA integrated

circuit), operation is limited to half-duplex, and signals to/from the transceiver are custom CMOS rather than more traditional RS-232/422 or other standard interconnects. In addition, support for packet framing and link establishment/maintenance (e.g. ARQ) is limited within the transceiver itself.

In return for these limitations, the volume and mass of the transceiver are two to three orders of magnitude lower than that of the transceivers on-board the Spirit and Opportunity rovers, and the power consumption is one to two orders of magnitude less. This tradeoff favors application on very small and/or low mass vehicles such as micro-rovers, balloons, aerobots, and networked landers. To the extent possible, the microtransceiver is also designed to operate with low radiation shielding and minimal thermal insulation. All of these features contribute to final system solutions offering expanded exploration opportunities.

Finally, the design is partitioned into multiple die rather than targeting a "single-chip" solution. This decision was made to minimize development risk and to provide maximum flexibility. The multi-die decision has minimal impact on the overall mass/size/power goal while offering better paths for upgrading or retargeting to applications outside the Mars role for which it is being designed.

#### 4. RFIC ARCHITECTURE

The detailed architecture of the RFIC die is shown in Figure 4. For reliability and development risk-reduction, it employs relatively traditional direct-conversion transmitter and superheterodyne receiver architectures operated in a half-duplex mode. Both share a common UHF synthesizer which generates the necessary quadrature sinusoids needed for IQ modulation and for image-reject mixing. The synthesizer operating frequency, as well as most control functions of the IC, are programmed through a 3-wire serial bus with 3V CMOS logic levels.

A single synthesizer is feasible due to the half-duplex operating mode. This conserves power and die area and also allows the elimination of bulky duplex filters. In addition, it permits the co-location of power amplifier circuits on the same die as the sensitive receive circuits. During transmit, the synthesizer is programmed to the desired output frequency (e.g. 404.4 MHz) by the digital baseband/control IC. During receive, the synthesizer is programmed to the receive frequency (e.g. 435.6 MHz) plus the IF (nominally 10.7 MHz). This high-side injection strategy is used to provide better tracking of the TCXO and IF filter changes with temperature [3].

Within an application circuit, the system's antenna is connected simultaneously to the RFIC's LNA input and one

of the PA outputs. During transmit mode, a reflective switch at the input to the LNA steers the transmit signal to the antenna and protects the LNA from the large voltages associated with 100 mW to 1 W operation (when using the optional external 1 W PA IC). During receive, the transmitter outputs become reflective terminations so that the majority of the receive signal power is routed to the LNA, minimizing noise figure. These reflective terminations are represented by the open-circuit switches shown in Figure 4, although the actual implementations employ parallel-resonant tanks which are combined with impedance-matching circuits. Details of the resonant switch design can be found in reference [6].

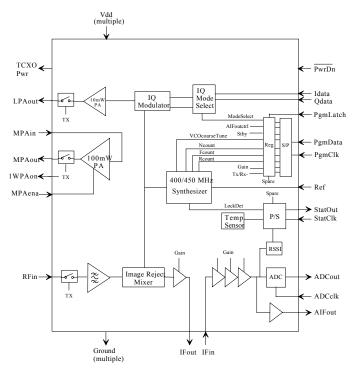


Figure 4. Transceiver RFIC block diagram

## A. Receive-mode Operation

In receive mode, the switch in-line with the RFin signal of Figure 4 is closed and the signal encounters approximately 16 dB of gain in the tuned-RF LNA followed by approximately 20 dB of gain within the image-reject (IR) mixer. IR mixing is employed to minimize noise figure only. Actual image signal rejection is not a critical performance parameter within Similarly, since the interference the Mars environment. environment at Mars is more benign than that in terrestrial radio systems (e.g. cell phones) low input compression can be traded for low power operation. Further, to optimize noise figure performance, only limited filtering provided by the matching circuits is used in front of the LNA. These issues should be carefully considered by the system designer to guarantee electromagnetic compatibility with other electronics onboard the scout craft.

Following downconversion, the received signal is amplified at

a 10.7 MHz intermediate frequency. The IF signal is routed off-chip to an IF filter which restricts the bandwidth to approximately 300 kHz. This bandwidth provides the spectrum narrowing required to prevent saturation of later stages of the IF amplifiers by broadband downconverted noise. In addition, it is needed to provide adequate prefiltering for 1-bit analog-to-digital conversion and subsequent demodulation functions the digital in modem/control IC.

The 1-bit ADC is clocked by an off-chip signal provided to it from the TCXO or the digital modem/control IC. The nominal clock frequency is specified as 19.200 MHz to prevent harmonics of the clock from interfering with receive signal frequencies and to allow for integer division to data clocks which conform to Proximity-1 recommended rates up to 256 kbps (division by 75). This clock will typically be the same signal as the synthesizer reference input, and provided by the TCXO. For applications which provide their own ADC functions, an un-digitized IF output is also provided.

The level of the IF signal entering either the on-chip or offchip ADC circuits can be controlled through gain control bits shifted into the RFIC together with the synthesizer frequencycontrol bits. 12 bits are used to provide approximately 72 dB of gain control in approximately 6 dB steps. The external controller IC can monitor the level out of the IF chain through the receive signal-strength indicator (RSSI) circuit periodically to update the gains and form a digital AGC loop. The RSSI circuit provides 2 bits of resolution as a digital code shifted out of the RFIC using the StatClk signal. Additional bits shifted out with the RSSI code include an indication of die temperature and bits determining if the synthesizer is locked.

#### B. Transmit-mode Operation

Transmit mode is entered by programming the synthesizer for the desired frequency and then bringing pin Tx high. This signal enables one or both PA circuits depending on the state of MPAena and shuts down unneeded receive circuits to save power. The signal also controls internal power sequencing circuitry to provide needed spurious emission reduction and protection of the LNA.

Following assertion of Tx, the digital modem/control IC monitors TxOn which indicates when power sequencing is complete and a carrier is being transmitted. Once TxOn is asserted, data may be fed to the IQ modulator in either analog or digital form. Selection of analog or digital inputs to the IQ modulator is provided by a control bit in the programming data that accompanies the synthesizer frequency and receive gain-control bits.

#### C. Power Control

The transceiver contains internal power management circuits to provide for sleep-mode power conservation as well as near-complete power down of both itself and the TCXO. Nominal power consumption on receive is 40 mW. This can be reduced to less than 0.5 mW using a wake/sleep duty cycle of 1 %, and to proportionally lower consumption with lower duty cycles.

# 5. DIGITAL MODEM / CONTROL IC

The top-level architecture of the digital IC is shown in Figure 5. In transmit mode, this IC provides forward error correction (FEC) convolutional coding compatible with Proximity-1 protocols, and optional packet framing functions. Residual carrier BPSK and suppressed carrier BPSK and QPSK are accommodated by a logical CMOS outputs for inphase and quadrature data components to the baseband inputs of the RFIC complex modulator. In receive mode, the IC handles the demodulation task as well as bit/frame synchronization.

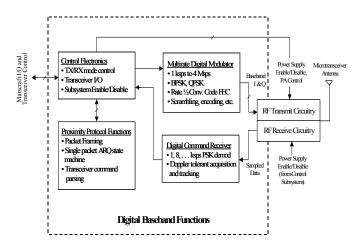


Figure 5. Digital Modem/Control IC functions.

A Discrete Fourier Transform (DFT)-based algorithm allows acquisition of BPSK or QPSK modulated signals over a +/- 50 kHz search range. This extended range is provided to address frequency drift of the TCXO at temperatures below its rated range [3] as well as aging and Doppler issues. In order to provide a modest compromise between accurate frequency estimation and processing complexity, the DFT is structured as a cascade of coarse and fine frequency estimation stages. Example performance for the first stage is shown in figure 6.

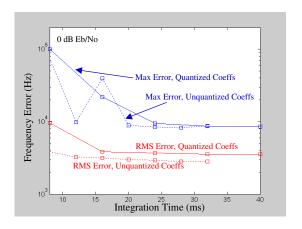


Figure 6. First-stage frequency estimation

A 16 point DFT is employed in the estimation to reduce the frequency uncertainty to less than 10 kHz within the first stage with additional fine-tuning performed in similar follow-on processing. These results correspond to a sampling frequency of 128 kHz of an 8 ksps BPSK signal received with 0 dB Eb/No. For sufficiently long integration intervals, there is good agreement between floating and fixed point performance. The non-monotonic behavior of the fixed-point, maximum error curve is a result of limited simulation trials for short integration periods. Due to the relatively low sampling rates in the frequency estimation processing, hardware re-use of the 16-point DFT is employed resulting in savings in required gate utilization.

Additional functions of the digital IC include control for the receiver and synthesizer circuits. At regular intervals, the IC monitors the RSSI output of the receiver and updates receiver gain settings to adjust for signal strength variations during an orbital pass. In addition, the VCO within the RFIC's synthesizer contains frequency range settings which are periodically monitored and updated to retain lock as IC or host PC-board temperatures vary.

# 6. IC PROTOTYPING AND TEST

The custom RF circuits and digital signal processing algorithms discussed above are being developed at Kansas State University and the California Institute of Technology's Jet Propulsion Laboratory respectively, with oversight on circuit and IC process issues from Peregrine Semiconductor Corporation. To-date, initial prototyping of the receiver circuits within the RFIC and of the associated frequency acquisition, demodulation, and synchronization circuits has been completed. All circuits are being designed to work over the Mars temperature range of –100 to +25 C and to tolerate radiation exposure of up to 100 krad total dose.

A photograph of the first RFIC prototype die, which includes all receiver circuits is shown in Figure 6. The synthesizer circuits are in the upper right quadrant. The LNA and RF

switch functions are in the lower left quadrant, and the remainder of the receiver circuits are in the lower right. Test structures to allow for measurement and optimization of individual cells in future fabs are in the upper left.

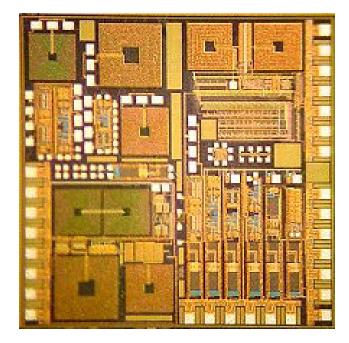


Figure 6. Die photograph of 1<sup>st</sup> spin receiver circuitry.

Initial testing, shown in Figures 7 and 8 indicates successful operation of all circuits, with some design centering and modifications needed within the tuned-RF amplifier circuits of the LNA.

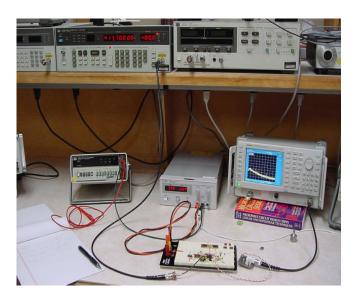


Figure 7. Early prototype testing.



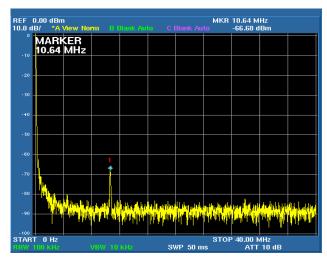


Figure 8. IF output before and immediately after IF filter. (-100 dBm RF input, 100 kHz resolution bandwidth)

## 7. OPTIMIZATIONS AND TRANSMITTER DESIGN

In addition to achieving operation over temperature, issues such as sensitivity, spurious responses, and stability of circuits are critical in the RFIC design. While the use of differential circuits and extensive filtering within the receive chain achieved the desired stability, minor problems with noise figure and spurious responses were noted. The higher than expected noise figure was traced to a combination of low gain within the LNA and higher than expected noise within the mixer. Both problems are being addressed in the 2<sup>nd</sup> spin design of the LNA which boosts its gain by approximately 15 dB at the expense of raising its power consumption from 1mA to 1.5 mA. The spurious response issue is assessed by monitoring the filtered IF output spectrum with low-level RF signals applied. An example spectrum is shown in Figure 9 for the case of a -80 dBm, 435.7 MHz BPSK-modulated signal applied to the input of the receiver. The IF filter passband contains a spurious response at 100 kHz above the downconverted signal. This spur results from the 353rd

harmonic of the 1.2 MHz reference used within the synthesizer (19.2 MHz internally divided by 16) and is believed to be coupled either through supply lines or magnetic fields intercepted by the LNA inductors. While this response is sufficiently outside the acquisition range of the digital demodulator IC, mitigation approaches are being applied in the next revision of the synthesizer circuits to reduce such spurs. These mitigation techniques include insertion of local bypass capacitors in the digital circuits to reduce the size of current loops, as well as use of a metal-3 ground plane above all digital circuits to provide magnetic shielding through image current production.

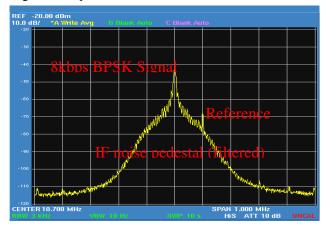


Figure 9. Output of IF filter showing detailed spurious behavior. (-80 dBm RF BPSK input, 3 kHz resolution bandwidth)

The layout of the second prototype of RFIC is shown in Figure 10. Clockwise from upper right, this die includes the 10, 100 mW power amplifier circuits, a revised synthesizer with the spurious mitigation techniques applied, test structures related to the power amplifier and synthesizer designs, and the revised LNA with downconversion mixer and pre-IF filter amplifiers included to assess revised system noise figure performance.

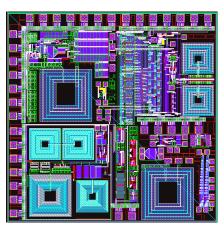


Figure 10. 2<sup>nd</sup> prototype RFIC layout including revised synthesizer and LNA, plus 10, 100 mW PA circuits.

The layout of Figure 10 was submitted to fabrication in October of 2005 and will be tested beginning in January of 2006. Additional fabrication runs are scheduled in 2006 to

complete the RFIC transceiver design and to implement the optional 1W PA circuit die. Testing at Mars temperature will begin in November 2005 and continue throughout the end of the project in 2007. The overall performance expected for the final design is summarized in Table 1.

Table 1. Micro-transceiver Target Specifications

Parameter	Тур	Units
Power Supply Voltage	3.3	Volts
Power Consumption		
Transmit (10mW out)	50	mW
Transmit (100 mW out)	250	mW
Transmit (1 W out)	3	W
Receive (100% duty cycle)	40	mW
Tuning range		
Transmit	390 - 410	MHz
Receive	430 - 450	MHz
Tuning step size	< 100	kHz
TX frequency error		
-40 to +50C	< 10	ppm
-100 to -40C	< 150	ppm
Transmit bit rate	1 to 4096	ksps
Receive symbol rate	1 to 8	ksps
Receive sensitivity (1kbps)	-130	dBm

# 8. SUMMARY AND CONCLUSIONS

A UHF micro-transceiver intended for future Mars scout missions and other space proximity links has been described. The goal is to provide a transceiver which is two to three orders of magnitude smaller, lighter, and lower-power than those currently available. While a number of tradeoffs have been made to achieve these goals, including limitation to half-duplex mode, reduced data rates, and support for a minimal subset of Proximity-1 protocols, the final transceiver should enable the development of new types of Mars exploration craft ranging from low-mass network ground sensors to airplanes and balloons. Results of prototyping to-date suggest that the target specifications for the micro-transceiver are reachable.

#### **ACKNOWLEDGMENTS**

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#### REFERENCES

- G. Lyons, "Commercial SOS technology for radiation-tolerant space applications," IEEE Radiation Effects Data Workshop, 24 July 1998, Page(s): 96 –99
- [2] R. Reedy, J. Cable, D. Kelly, M. Stuber, F. Wright, and G. Wu, "UTSi CMOS: A Complete RF SOI Solution", Technical Note at http://www.peregrine-semi.com/pdf\_utsi\_utsicmoscomplete.pdf
- [3] Y. Tugnawat and W. Kuhn, "Low temperature Performance of COTS Electronic Components for Future MARS Missions," University of Idaho 12<sup>th</sup> NASA Symposium on VLSI Design, Oct 4-5, 2005.
- [4] Proximity-1 Space Link Protocol Final Draft Recommendation for Space Data System Standards, CCSDS 211.0-R-3.2. Red Book. Issue 3.2. September 2002. http://www.ccsds.org/rpa225/CCSDS-211.0-R-3.2.pdf
- [5] N. Lay, C. Cheetham, H. Mojaradi, J. Neal, "Developing Low Power Transceiver Technologies for In Situ Communications Applications", *Interplanetary Networks Progress Report*, No. 42-147, Jet Propulsion Laboratory, California Institute of Technology, Pasadena, CA, November 15, 2001. http://ipnpr.jpl.nasa.gov/tmo/progress\_report/42-147/title.htm.
- [6] W. B. Kuhn, M. Mojarradi, and A. Moussessian, "A resonant switch for LNA protection in watt-level CMOS transceivers," IEEE Transactions on Microwave Theory and Techniques, IEEExplore, pp. 2819-2825, September 2005.

#### **BIOGRAPHIES**

William B. Kuhn received a B.S. degree in Electrical Engineering



in 1979 from Virginia Tech, Blacksburg, VA, an M.S. degree in Electrical Engineering in 1982 from the Georgia Institute of Technology, Atlanta, GA, and a Ph.D. degree from Virginia Tech in 1996. From 1979 to 1981 he was with Ford Aerospace and Communications Corporation, Palo Alto, CA where he designed radio receiver equipment. From 1983 to 1992 he was with the Georgia Tech

Research Institute, Atlanta, GA working primarily in radar signal analysis and mixed-signal circuit simulator development. In 1996, he joined Kansas State University, Manhattan, KS as an Assistant Professor, later becoming an Associate Professor in 2000. He currently teaches courses in communications theory, radio and microwave circuit/system design, and VLSI. His research is targeted at low-power radio electronics in CMOS, BiCMOS, and SOI technologies.

Dr. Kuhn received the Bradley Fellowship in 1993 from Virginia Tech and a Faculty Early Career Development (CAREER) award from the National Science Foundation in 1999. He is also the recipient at K-State of the Hollis Award for Excellence in Undergraduate Teaching in 2001, the Eta Kappa Nu distinguished faculty award in 2002 and 2003, and the Paslay Professorship in Electrical and Computer Engineering in 2004.

Norman E. Lay received a B.S. degree in Electrical Engineering in 1983 from Columbia University, New York, NY, an M.S. degree in Electrical Engineering in 1984 from Stanford University, Stanford, CA, and a Ph.D. degree from the University of Southern California in 1996. From 1984 to 1986 he was with the General Electric Corporate Research and Development Center, Schenectady, NY where he developed and implemented real-time digital signal processing algorithms for voice compression and mobile radio modem applications. In 1986, he joined the Jet Propulsion Laboratory, Pasadena, CA. While at the Jet Propulsion Laboratory,

he has been involved in the development of advanced technologies for satellite, terrestrial and deep space communications. These have included L- and Ka-band mobile satellite communications, airborne relays, miniaturized transceivers for in situ communications and high rate ground receivers for near-earth and deep space links. Recently, he has supported the development of advanced communications waveforms for next generation DoD satellite communications systems. He is a technical group supervisor in the Communications Architectures and Research Section.

Edwin Grigorian is a senior member of engineering staff at Jet



Propulsion Laboratory (JPL). He has been at the JPL since 1990. Prior to that he was with Teledyne Brown Engineering in Huntsville, AL and at MSFC developing electronics for various materials processing experiments on-board the shuttle middeck & the Spacelab. Some of his recent work has included the design and integration of multi-Watt fully integrated CMOS power amplifiers and drivers for an L-band radar

T/R module, design of FPGA and low-power ASIC-based digital radios for UHF proxmity links, and the digital design of a neural prosthetic implant mixed-signal ASIC. He earned his BSEE in1985 and his MSEE in 1989, both from the University of Alabama in Huntsville. He also obtained his PE license in 1990. Currently, he is pursuing his Ph.D. in Electrical Engineering at the University of Southem California specializing in design of RFICs for Wireless Communications.